

# **Engineering/Process Change Notice**

ECN/PCN No.: 4128

For Manufacturer						
Product Description: PLASTIC SMD MEMS OSCILLATOR	Abracon Part Numb	er / Part Series: K33	☐ Documentation only☐ ECN	Series     □ Part Number		
			⊠ EOL	- Part Number		
Affected Revision:	New Revision:	OL	Application:	<ul><li>☐ Safety</li><li>☒ Non-Safety</li></ul>		
Prior to Change:  Active  https://abracon.com/datasheets/Ecliptek/EMK33.pdf						
After Change: EOL						
Cause/Reason for Change: Discontinuation of manufacturing capability.						
	Chan	ge Plan				
Effective Date: 2/7/2022	Additional Remarks: N/A					
Change Declaration: N/A						
Issued Date:	Issued By:		Issued Department:			
2/7/2022	Brooke Cushman Product Engineer		Engineerir	ng		
Approval:	Approval:		Approval:			
Thomas Culhane Engineering Director	Reuben Quintanilla Quality Director		Ying Huang Purchasing Director			
	For Abrac	on EOL only				
Last Time Buy (if applicable): 5/7/2022	Alternate Part Nun		ber / Part Series: ASEDV (3.2x2.5mm)			
Additional Approval:	Additional Approval:		Additional Approval:			
Customer Approval (If Applicable)						
Qualification Status:  Note: It is considered approved if there is n		□ Not accepted	r FCN/PCN is released			
Customer Part Number:	Customer Project:					
Company Name:	Company Representative:		Representative Signature	:		
Customer Remarks:						



Form #7020 | Rev. G | Effective: 02/22/2021 |













## **REGULATORY COMPLIANCE**











## **ITEM DESCRIPTION**

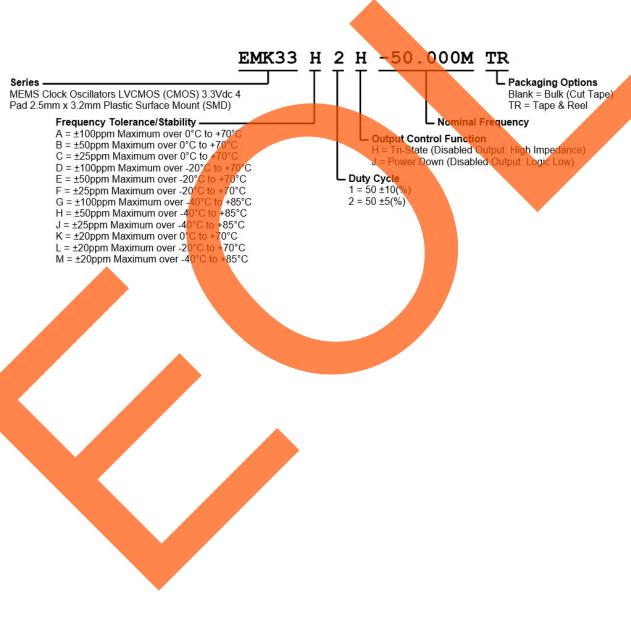
MEMS Clock Oscillators LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Plastic Surface Mount (SMD)

ELECTRICAL SPECIFICAT	TIONS
Nominal Frequency	1MHz to 125MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, and Output Load Change ±100ppm Maximum over 0°C to +70°C ±50ppm Maximum over 0°C to +70°C ±25ppm Maximum over 0°C to +70°C ±20ppm Maximum over 0°C to +70°C ±50ppm Maximum over -20°C to +70°C ±50ppm Maximum over -20°C to +70°C ±25ppm Maximum over -20°C to +70°C ±20ppm Maximum over -20°C to +70°C ±20ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C ±20ppm Maximum over -40°C to +85°C ±20ppm Maximum over -40°C to +85°C
Aging at 25°C	±1.5ppm Max <mark>imum F</mark> irst Year
Supply Voltage	3.3Vdc ±10%
Input Current	No Load 5mA Maximum over Nominal Frequency of 1MHz to 20MHz 6mA Maximum over Nominal Frequency of 20.000001MHz to 50MHz 7mA Maximum over Nominal Frequency of 50.000001MHz to 80MHz 9mA Maximum over Nominal Frequency of 80.000001MHz to 125MHz
Output Voltage Logic High (V <sub>OH</sub> )	IOH = -4mA 90% of Vdd Minimum
Output Voltage Logic Low (V <sub>OL</sub> )	IOL = +4mA 10% of Vdd Maximum
Rise/Fall Time	Measured from 20% to 80% of waveform  1.2nSec Typical, 3nSec Maximum
Duty Cycle	Measured at 50% of waveform 50 ±10(%) 50 ±5(%)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Tri-State (Disabled <mark>Output: H</mark> igh Impedance) Power Down (D <mark>isabled Output: Logic Low)</mark>
Output Control Input Voltage Logic High (Vih)	70% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	30% of Vdd Maximum to Disable Output
Power Down Output Enable Time	5mSec Maximum (Disabled Output: Logic Low)
Tri-State Output Enable Time	150nSec Maximum (Disabled Output: High Impedance)
Power Down Output Disable Time	150nSec Maximum (Disabled Output: Logic Low)
Tri-State Output Disable Time	150nSec Maximum (Disabled Output: High Impedance)
Standby Current	10μA Maximum (Disabled Output: Logic Low)
Period Jitter (RMS)	2pSec Typical, 4pSec Maximum



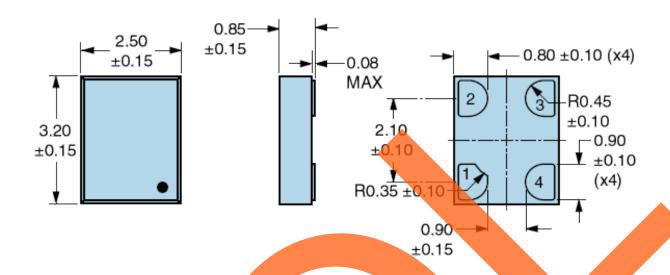
RMS Phase Jitter (Fj = 900kHz to 7.5MHz; Random)	0.5pSec Typical, 1pSec Maximum
RMS Phase Jitter (Fj = 12kHz to 20MHz; Random)	1.5pSec Typical, 3pSec Maximum
Start Up Time	5mSec Maximum
Storage Temperature Range	-65°C to +150°C

#### **PART NUMBERING GUIDE**

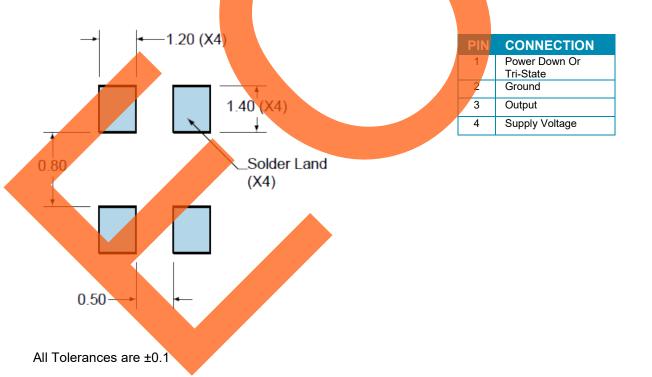




#### **MECHANICAL DIMENSIONS**



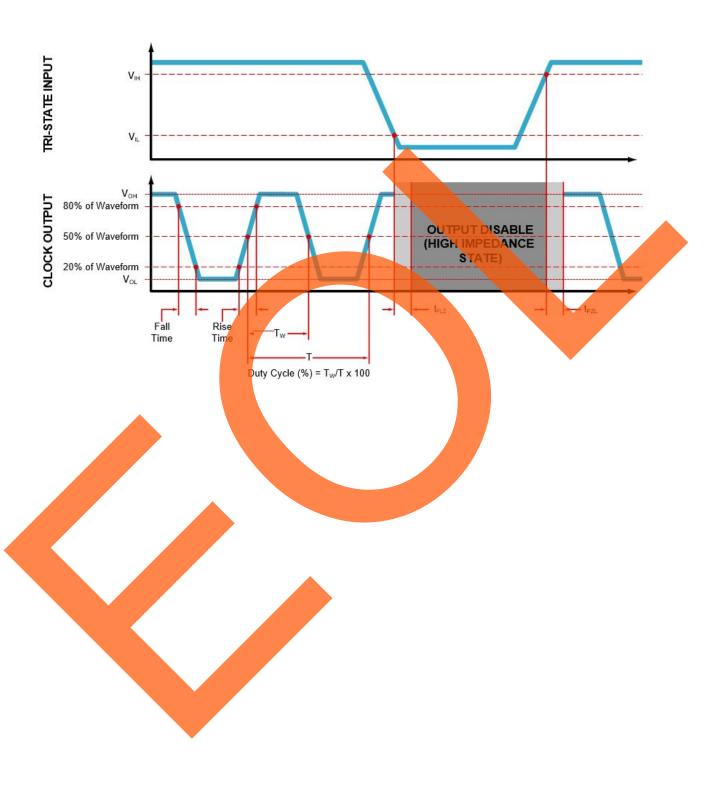
## SUGGESTED SOLDER PAD LAYOUT



**All Dimensions in Millimeters** 

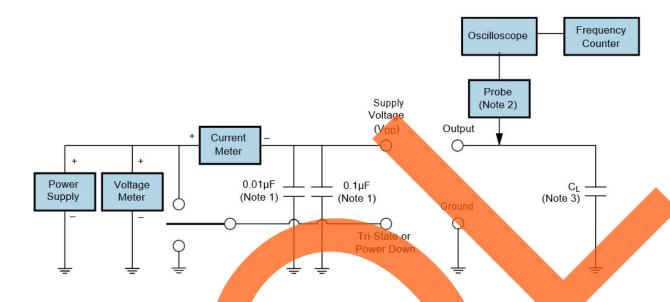


## **OUTPUT WAVEFORM & TIMING DIAGRAM**





#### **TEST CIRCUIT FOR CMOS OUTPUT**



- Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less Than 2mm) to the package ground and supply voltage pin is required.

  Note 2: A low input capacitance (<12pF), 10X Attentuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz)
- Passive probe is recommended.
- Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.



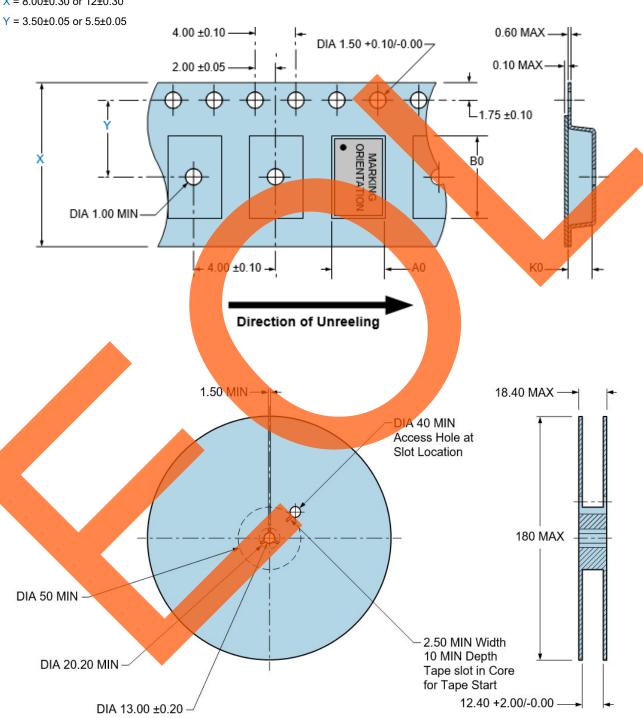
## **TAPE & REEL DIMENSIONS**

Quantity per Reel: 1,000 Units

All Dimensions in Millimeters

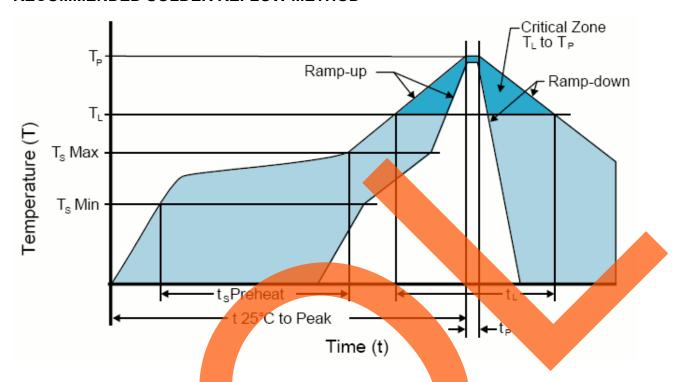
Compliant to EIA-481

 $X = 8.00\pm0.30 \text{ or } 12\pm0.30$ 





## **RECOMMENDED SOLDER REFLOW METHOD**



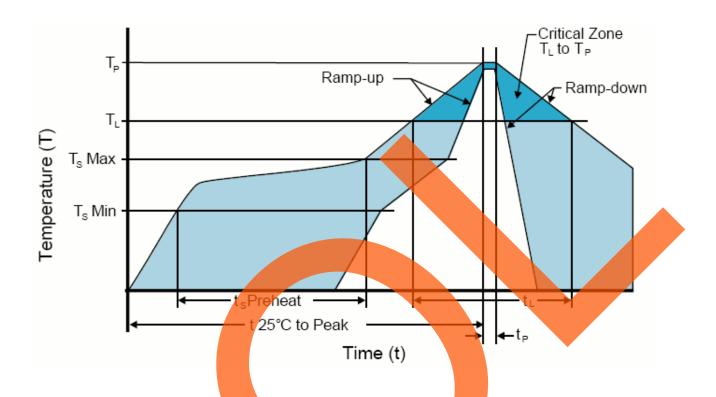
HIGH TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>S</sub> MIN)	150°C	
- Temperature Typical (T <sub>S</sub> TYP)	175°C	
- Temperature Maximum(T <sub>s</sub> MAX)	200°C	
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	217°C	
- Time (t∟)	60 - 150 Seconds	
Peak Temperature (T <sub>P</sub> )	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(Tp Target)	250°C +0/-5°C	
Time within 5°C of actual peak (tp)	20 - 4 <mark>0 Seconds</mark>	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

## **High Temperature Manual Soldering**

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



## **RECOMMENDED SOLDER REFLOW METHOD**



LOW TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>s</sub> MIN)	N/A	
- Temperature Typical (T <sub>S</sub> TYP)	150°C	
- Temperature Maximum(T <sub>s</sub> MAX)	N/A	
- Time (t <sub>s</sub> MíN)	60 - 120 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (TL)	150°C	
- Time (t <sub>L</sub> )	200 Seconds Maximum	
Peak Temperature (T <sub>P</sub> )	240°C Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	240°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (t₂)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

## **Low Temperature Manual Soldering**

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

# **ABRACON:**

<u>EMK33H2H-27.000M</u> <u>EMK33H2H-125.000M</u> <u>EMK33H2H-106.250M</u> <u>EMK33H2H-50.000M</u> <u>EMK33H2H-100.000M</u> EMK33H2H-80.000M EMK33H2H-50.000M TR